

Application Data Sheet

Application Information

Application Type:: Regular
Subject Matter:: Utility
Suggested classification::
Suggested Group Art Unit::
CD-ROM or CD-R?:: None
Title:: Super-thin high speed flip chip package
Attorney Docket Number:: CPAC 1010-2 US
Request for Early Publication?:: No
Request for Non-Publication?:: No
Suggested Drawing Figure::
Total Drawing Sheets::
Small Entity?:: No
Petition included?:: No
Secrecy Order in Parent Appl.?:: No

Applicant Information

Applicant Authority Type:: Inventor
Primary Citizenship Country:: US
Status:: Full Capacity
Given Name:: Rajendra
Family Name:: PENDSE
City of Residence:: Fremont
State or Province of Residence:: CA
Country of Residence:: US
Street of mailing address:: 5245 Diamond Common
City of mailing address:: Fremont
State or Province of mailing address:: CA
Country of mailing address:: US
Postal or Zip Code of mailing address:: 94555

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Applicant Authority Type:: Inventor
Primary Citizenship Country:: US
Status:: Full Capacity
Given Name:: Samuel
Family Name:: TAM
City of Residence:: Daly City
State or Province of Residence:: CA
Country of Residence:: US
Street of mailing address:: 102 Ashland Drive
City of mailing address:: Daly City
State or Province of mailing address:: CA
Country of mailing address:: US
Postal or Zip Code of mailing address:: 94015

Correspondence Information

Correspondence Customer Number:: 22470

Representative Information

Representative Customer Number::	22470	
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Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Non-Provisional of	60/272,236	02/27/01

Assignee Information

Assignee name:: ChipPAC, Inc.
Street of mailing address:: 47400 Kato Road
City of mailing address:: Fremont
State or Province of mailing address:: CA
Country of mailing address:: US
Postal or Zip Code of mailing address:: 94538